

## Electronic Patent Application Fee Transmittal

<b>Application Number:</b>	10616097				
<b>Filing Date:</b>	08-Jul-2003				
<b>Title of Invention:</b>	Multiple-step electrodeposition process for direct copper plating on barrier metals				
<b>First Named Inventor/Applicant Name:</b>	Zhi-Wen Sun				
<b>Filer:</b>	Keith Patrick Taboada				
<b>Attorney Docket Number:</b>	AMAT/8241/CMP/ECP/RKK				
Filed as Large Entity					
<b>Utility Filing Fees</b>					
<b>Description</b>		<b>Fee Code</b>	<b>Quantity</b>	<b>Amount</b>	<b>Sub-Total in USD(\$)</b>
<b>Basic Filing:</b>					
<b>Pages:</b>					
<b>Claims:</b>					
<b>Miscellaneous-Filing:</b>					
<b>Petition:</b>					
<b>Patent-Appeals-and-Interference:</b>					
<b>Post-Allowance-and-Post-Issuance:</b>					
<b>Extension-of-Time:</b>					
Extension - 1 month with \$0 paid	1251	1	120	120	

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
<b>Miscellaneous:</b>				
Request for continued examination	1801	1	790	790
<b>Total in USD (\$)</b>				<b>910</b>